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This standard includes the English version of the European Standard.

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Programmable controllers - Part 9: Single-drop digital communication interface for small sensors and actuators (SDCI)

(IEC 61131-9:2013)

Automates programmables -
Partie 9: Interface de communication numérique point à point pour petits capteurs et actionneurs (SDCI)
(CEI 61131-9:2013)

Speicherprogrammierbare Steuerungen -
Teil 9: Schnittstelle für die Kommunikation mit kleinen Sensoren und Aktoren über eine Punkt-zu-Punkt-Verbindung
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The text of document 65B/874/FDIS, future edition 1 of IEC 61131-9, prepared by SC 65B, "Measurement and control devices", of IEC/TC 65, "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61131-9:2013.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2014-07-16
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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60870-5-1:1990	NOTE	Harmonised as EN 60870-5-1:1993 (not modified).
IEC 61158-2	NOTE	Harmonised as EN 61158-2 (not modified).
IEC/TR 62453-61	NOTE	Harmonised as CLC/TR 62453-61 (not modified).
ISOIEC 7498-1	NOTE	Harmonised as EN ISOIEC 7498-1 (not modified).

Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

Publication	Year	Title	EN/HD	Year
IEC 60947-5-2	-	Low-voltage switchgear and controlgear - Part 5-2: Control circuit devices and switching elements - Proximity switches	EN 60947-5-2	-
IEC 61000-4-2	-	Electromagnetic compatibility (EMC) - Part 4-2: Testing and measurement techniques - Electrostatic discharge immunity test	EN 61000-4-2	-
IEC 61000-4-3	-	Electromagnetic compatibility (EMC) - Part 4-3: Testing and measurement techniques - Radiated, radio-frequency, electromagnetic field immunity test	EN 61000-4-3	-
IEC 61000-4-4	-	Electromagnetic compatibility (EMC) - Part 4-4: Testing and measurement techniques - Electrical fast transient/burst immunity test	EN 61000-4-4	-
IEC 61000-4-5	-	Electromagnetic compatibility (EMC) - Part 4-5: Testing and measurement techniques - Surge immunity test	FprEN 61000-4-5	-
IEC 61000-4-6	-	Electromagnetic compatibility (EMC) - Part 4-6: Testing and measurement techniques - Immunity to conducted disturbances, induced by radio-frequency fields	FprEN 61000-4-6	-
IEC 61000-4-11	-	Electromagnetic compatibility (EMC) - Part 4-11: Testing and measurement techniques - Voltage dips, short interruptions and voltage variations immunity tests	EN 61000-4-11	-
IEC 61000-6-2	-	Electromagnetic compatibility (EMC) - Part 6-2: Generic standards - Immunity for industrial environments	EN 61000-6-2 + corr. September	- -
IEC 61000-6-4	-	Electromagnetic compatibility (EMC) - Part 6-4: Generic standards - Emission standard for industrial environments	EN 61000-6-4	-
IEC 61076-2-101	-	Connectors for electronic equipment - Product requirements - Part 2-101: Circular connectors - Detail specification for M12 connectors with screw-locking	EN 61076-2-101	-
IEC 61131-1	-	Programmable controllers - Part 1: General information	EN 61131-1	-

Publication	Year	Title	EN/HD	Year
IEC 61131-2	-	Programmable controllers - Part 2: Equipment requirements and tests	EN 61131-2[1)]	-
IEC/TR 62390	-	Common automation device - Profile guideline	-	-
ISO/IEC 646	1991	Information technology - ISO 7-bit coded character set for information interchange	-	-
ISO/IEC 2022	-	Information technology - Character code structure and extension techniques	-	-
ISO/IEC 10646	-	Information technology - Universal Coded Character Set (UCS)	-	-
ISO/IEC 10731	-	Information technology - Open Systems Interconnection - Basic reference model - Conventions for the definition of OSI services	-	-
ISO 1177	-	Information processing - Character structure for start/stop and synchronous character-oriented transmission	-	-
IEEE 754	2008	Binary floating-point arithmetic	-	-

[1)] EN 61131-2 is superseded by EN 61010-2-201:2013, which is based on IEC 61010-2-201:2013.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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PROGRAMMABLE CONTROLLERS –

Part 9: Single-drop digital communication interface for small sensors and actuators (SDCI)

FOREWORD

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International Standard IEC 61131-9 has been prepared by subcommittee 65B: Measurement and control devices, in collaboration with subcommittee 65C: Industrial networks, of IEC technical committee 65: Industrial-process measurement, control and automation.

The text of this standard is based on the following documents:

FDIS	Report on voting
65B/874/FDIS	65B/889/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 61131 series, published under the general title *Programmable controllers*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

0.1 General

IEC 61131-9 is part of a series of standards on programmable controllers and the associated peripherals and should be read in conjunction with the other parts of the series.

Where a conflict exists between this and other IEC standards (except basic safety standards), the provisions of this standard should be considered to govern in the area of programmable controllers and their associated peripherals.

The increased use of micro-controllers embedded in low-cost sensors and actuators has provided opportunities for adding diagnosis and configuration data to support increasing application requirements.

The driving force for the SDCI (IO-Link™[1]) technology is the need of these low-cost sensors and actuators to exchange this diagnosis and configuration data with a controller (PC or PLC) using a low-cost, digital communication technology while maintaining backward compatibility with the current DI/DO signals.

In fieldbus concepts, the SDCI technology defines a generic interface for connecting sensors and actuators to a Master unit, which may be combined with gateway capabilities to become a fieldbus remote I/O node.

Any SDCI compliant Device can be attached to any available interface port of the Master. SDCI compliant Devices perform physical to digital conversion in the Device, and then communicate the result directly in a standard format using "coded switching" of the 24 V I/O signalling line, thus removing the need for different DI, DO, AI, AO modules and a variety of cables.

Physical topology is point-to-point from each Device to the Master using 3 wires over distances up to 20 m. The SDCI physical interface is backward compatible with the usual 24 V I/O signalling specified in IEC 61131-2. Transmission rates of 4,8 kbit/s, 38,4 kbit/s and 230,4 kbit/s are supported.

The Master of the SDCI interface detects, identifies and manages Devices plugged into its ports.

Tools allow the association of Devices with their corresponding electronic I/O Device Descriptions (IODD) and their subsequent configuration to match the application requirements.

The SDCI technology specifies three different levels of diagnostic capabilities: for immediate response by automated needs during the production phase, for medium term response by operator intervention, or for longer term commissioning and maintenance via extended diagnosis information.

The structure of this standard is described in 4.8.

Conformity with IEC 61131-9 cannot be claimed unless the requirements of Annex G are met.

Terms of general use are defined in IEC 61131-1 or in the IEC 60050 series. More specific terms are defined in each part.

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[1] IO-Link™ is a trade name of the "IO-Link Consortium". This information is given for the convenience of users of this international Standard and does not constitute an endorsement by IEC of the trade name holder or any of its products. Compliance to this standard does not require use of the registered logos for IO-Link™. Use of the registered logos for IO-Link™ requires permission of the "IO-Link Consortium".

0.2 Patent declaration

The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of patents concerning the point-to-point serial communication interface for small sensors and actuators as follows, where the [xx] notation indicates the holder of the patent right:

DE 10030845B4 EP 1168271B1 US 6889282B2	[AB]	Fieldbus connecting system for actuators or sensors
EP 1203933 B1	[FE]	Sensor device for measuring at least one variable
DE 10 2004 035 831.1	[SI]	Operational status of a computer system is checked by comparison of actual parameters with reference values and modification to software if needed
DE 102 119 39 A1 US 2003/0200323 A1	[SK]	Coupling apparatus for the coupling of devices to a bus system

IEC takes no position concerning the evidence, validity and scope of these patent rights.

The holders of these patents rights have assured the IEC that they are willing to negotiate licences either free of charge or under reasonable and non-discriminatory terms and conditions with applicants throughout the world. In this respect, the statements of the holders of these patent rights are registered with IEC.

Information may be obtained from:

[AB]	ABB AG Heidelberg Germany
[FE]	Festo AG Esslingen Germany
[SI]	Siemens AG Otto-Hahn-Ring 6 81739 Munich Germany
[SK]	Sick AG Waldkirch Germany

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights other than those identified above. IEC shall not be held responsible for identifying any or all such patent rights.

ISO (www.iso.org/patents) and IEC (http://patents.iec.ch) maintain on-line data bases of patents relevant to their standards. Users are encouraged to consult the databases for the most up to date information concerning patents.

PROGRAMMABLE CONTROLLERS –

Part 9: Single-drop digital communication interface for small sensors and actuators (SDCI)

1 Scope

This part of IEC 61131 specifies a single-drop digital communication interface technology for small sensors and actuators SDCI (commonly known as IO-Link™[2]), which extends the traditional digital input and digital output interfaces as defined in IEC 61131-2 towards a point-to-point communication link. This technology enables the transfer of parameters to Devices and the delivery of diagnostic information from the Devices to the automation system.

This technology is mainly intended for use with simple sensors and actuators in factory automation, which include small and cost-effective microcontrollers.

This part specifies the SDCI communication services and protocol (physical layer, data link layer and application layer in accordance with the ISO/OSI reference model) for both SDCI Masters and Devices.

This part also includes EMC test requirements.

This part does not cover communication interfaces or systems incorporating multiple point or multiple drop linkages, or integration of SDCI into higher level systems such as fieldbuses.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60947-5-2, *Low-voltage switchgear and controlgear – Part 5-2: Control circuit devices and switching elements – Proximity switches*

IEC 61000-4-2, *Electromagnetic compatibility (EMC) – Part 4-2: Testing and measurement techniques – Electrostatic discharge immunity test*

IEC 61000-4-3, *Electromagnetic compatibility (EMC) – Part 4-3: Testing and measurement techniques – Radiated, radio-frequency, electromagnetic field immunity test*

IEC 61000-4-4, *Electromagnetic compatibility (EMC) – Part 4-4: Testing and measurement techniques – Electrical fast transient/burst immunity test*

IEC 61000-4-5, *Electromagnetic compatibility (EMC) – Part 4-5: Testing and measurement techniques – Surge immunity test*

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[2] IO-Link™ is a trade name of the "IO-Link Consortium". This information is given for the convenience of users of this international Standard and does not constitute an endorsement by IEC of the trade name holder or any of its products. Compliance to this standard does not require use of the registered logos for IO-Link™. Use of the registered logos for IO-Link™ requires permission of the "IO-Link Consortium".

IEC 61000-4-6, *Electromagnetic compatibility (EMC) – Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields*

IEC 61000-4-11, *Electromagnetic compatibility (EMC) – Part 4-11: Testing and measurement techniques – Voltage dips, short interruptions and voltage variations immunity tests*

IEC 61000-6-2, *Electromagnetic compatibility (EMC) – Part 6-2: Generic standards – Immunity for industrial environments*

IEC 61000-6-4, *Electromagnetic compatibility (EMC) – Part 6-4: Generic standards – Emission standard for industrial environments*

IEC 61076-2-101, *Connectors for electronic equipment – Product requirements – Part 2-101: Circular connectors – Detail specification for M12 connectors with screw-locking*

IEC 61131-1, *Programmable controllers – Part 1: General information*

IEC 61131-2, *Programmable controllers – Part 2: Equipment requirements and tests*

IEC/TR 62390, *Common automation device – Profile guideline*

ISO/IEC 646:1991, *Information technology – ISO 7-bit coded character set for information interchange*

ISO/IEC 2022, *Information technology – Character code structure and extension techniques*

ISO/IEC 10646, *Information technology – Universal Multiple-Octet Coded Character Set (UCS)*

ISO/IEC 10731, *Information technology – Open Systems Interconnection – Basic Reference Model – Conventions for the definition of OSI services*

ISO/IEC 19505 (all parts), *Information technology – Object Management Group Unified Modeling Language (OMG UML)*

ISO 1177, *Information processing – Character structure for start/stop and synchronous character oriented transmission*

IEEE Std 754-2008, *IEEE Standard for Floating-Point Arithmetic*

Internet Engineering Task Force (IETF): RFC 5905 – *Network Time Protocol Version 4: Protocol and Algorithms Specification;* available at < www.ietf.org >

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